

FEATURES

Small surface mounting type
Low reverse current and low forward voltage
High reliability

VOLTAGE RANGE

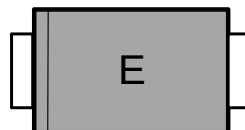
30Volts

CURRENT

0.2 Ampere

MECHANICAL DATA

- * Case: Molded plastic
- * Lead: Axial leads, solderable per MIL-STD-750, method 2026
- * Polarity: Polarity symbols marked on case



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

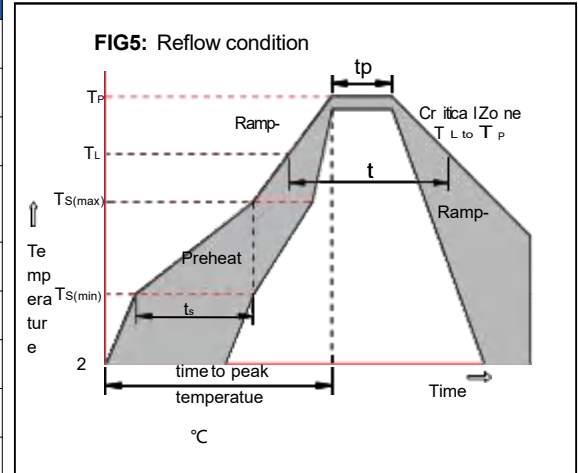
Parameter	Symbol	Limit	Unit
DC reverse voltage	V_R	30	V
Mean rectifying current	I_O	200	mA
Non-repetitive Peak Forward Surge Current@t=8.3ms	I_{FSM}	500	mA
Power dissipation	P_D	100	mW
Thermal Resistance Junction to Ambient	R_{JA}	1000	°C/W
Operating Junction Temperature Range	T_j	-40 ~ +125	°C
Storage Temperature Range	T_{stg}	-55 ~ +150	°C

Electrical Ratings @Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Forward voltage	V_F			0.45	V	$I_F=10mA$
Reverse current	I_R			0.5	μA	$V_R=10V$

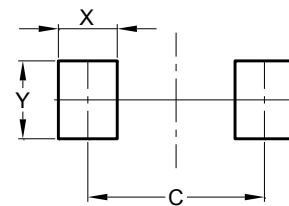
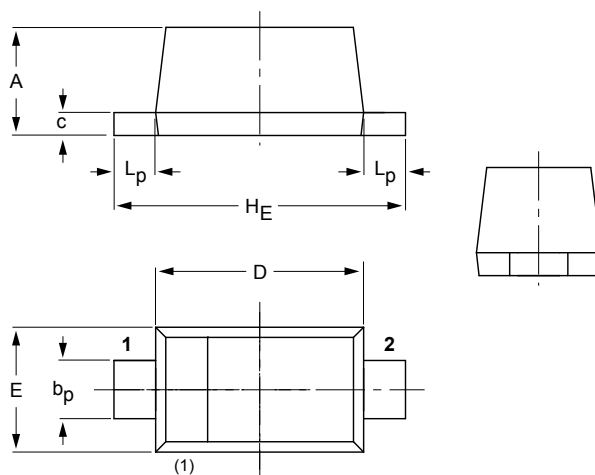
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max ($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

SOD-723



DIMENSIONS (mm are the original dimensions)

UNIT	A	bp	c	D	E	HE	Lp
mm	0.55 0.49	0.32 0.25	0.15 0.08	1.05 0.95	0.65 0.55	1.45 1.35	0.27 0.13

Dimensions	Value (in mm)
C	1.20
X	0.60
Y	0.70

